



IN THE SPECIFICATION

Page 4, line 22, after "thereinto." add --In Fig. 1, it is particularly to be noted that the terminal parts 30a, 30b and 30c are formed in clusters such that those of the terminal parts 30a, 30b and 30c within a same one of the terminal-forming areas 3a, 3b and 3c are closer together than those in different ones thereof.--.

Amend claim 1 as follows:

(Amended) A method of surface-mounting a plurality of electronic components having conductive connecting members to a plurality of specified terminal-forming areas of a target surface having terminal parts therein, said terminal parts being clustered such that those of said terminal parts within a same one of said terminal-forming areas are closer together than those of said terminal parts in different ones of said terminal-forming areas, said method comprising the steps of:

forming an anisotropic conductive layer on said target surface so as to span said plurality of terminal-forming areas;

placing said plurality of electronic components on said anisotropic conductive layer individually above said plurality of terminal-forming areas; and

pressing said plurality of electronic components to said anisotropic conductive layer so as to thereby cause said conductive connecting members of said plurality of electronic components to individually become adhered to and in electrically conductive relationship with a corresponding one of said terminal parts through said anisotropic conductive layer.